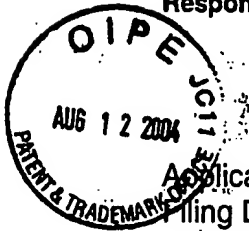


Application Serial No. 09/756,971
Response to August 3, 2004 OA

EV372460662

MI22-1572



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2827
Examiner D.A. Zarneke
Attorney's Docket No. MI22-1572
Customer No. 021567

Title: Methods of Forming Board-On-Chip Packages

RESPONSE TO AUGUST 3, 2004 FINAL OFFICE ACTION
PURSUANT TO 37 C.F.R. §1.116

To: Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

From: D. Brent Kenady
Tel. 509-624-4276; Fax 509-838-3424
Wells St. John P.S.
601 West First Avenue, Suite 1300
Spokane, WA 99201-3828

Responsive to the Final Office Action dated August 3, 2004, Applicant
amends and remarks as follows:

AMENDMENTS

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.